

REV LTR	DESCRIPTION	DATE	APPVD.
-	Orig. Release	02/15/08	JSN
A	Revised per ECN 2012-1	11/09/12	JSN
B	Revised per ECN 2014-1	03/26/14	JSN
C	Revised per ECN 2016-2	10/21/16	JSN

**FTTC11 Series**  
**CMOS/LVDS/LVEPCL/CML Output TCXO/VCTCXO**  
**FOR SPACE APPLICATIONS**  
**10MHz to 1400MHz**  
**( 5 x 7 mm, SMD, 1.8V, 2.5 V,3.3V )**

( Refer to Page 5 for Models with Reduced Screening & QCI )

## 6.0 Part Numbering Example:

FTTC11	-	L	S	3	J	D	T	100
		Output logic	Grade(Screening Level)	Voltage	* Frequency stability	Operating temperature range	Frequency tuning	Frequency
		H=CMOS	N=No Screening	3=+3.3V	G= 1.0 ppm	A= 0°C to +50°C	T=TCXO(No Vc)	MHz
		L=LVDS	I= Industrial Std	2=+2.5V	J = 2.0ppm	B= 0°C to +70°C	V=TCVCXO(With Vc)	
		P=LVPECL	B= MIL-PRF-55310,level B	1=+1.8V	K= 6.0ppm	C= -20°C to +70°C		
		M=CML	S= MIL-PRF-55310,level S ,50krad(Si) total dose		H= 8.0 ppm	D= -40°C to +85°C		
			V= MIL-PRF-55310,level S ,80krad(Si) total dose		L= 9.2ppm	E= -55°C to +105°C		
			R= MIL-PRF-55310,level S ,100krad(Si) total dose		E= 10 ppm	F= -55°C to +125 °C		

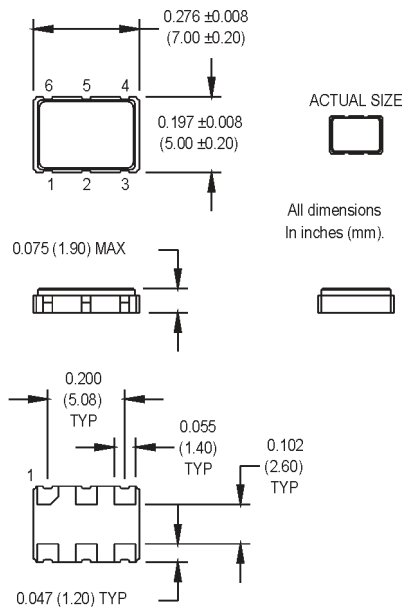
\*Note: Frequency stability=(Fmax-Fmin)/2

### Freq. Vs Temp Availability

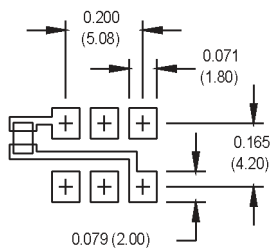
Temp (°C)	G: ±1.0ppm	J: ±2.0ppm	K: ±6.0ppm	H: ±8.0ppm	L: ±9.2ppm
A: 0°C to +50°C	♦	♦	♦	♦	♦
B: 0°C to +70°C	♦	♦	♦	♦	♦
C: -20°C to +70°C	o	♦	♦	♦	♦
D: -40°C to +85°C	o	♦	♦	♦	♦
E: -55°C to +105°C	o	o	o	♦	♦
F: -55°C to +125°C	o	o	o	o	♦

o Contact Factory  
♦ available

### Product Dimension:



### SUGGESTED SOLDER PAD LAYOUT



### Pin connections:

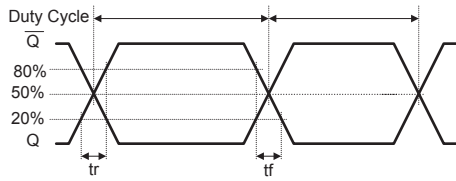
LVPECL, LVDS,CML

Pin #	Connection
1	N/C or Vc
2	N/C
3	GND
4	Output
5	Output
6	Supply Voltage

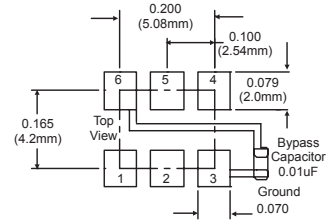
### CMOS

Pin #	Connection
1	N/C or Vc
2	N/C
3	GND
4	Output
5*	N/C
6	Supply Voltage

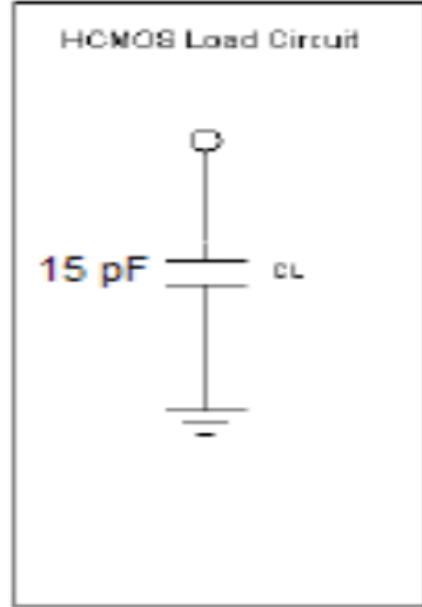
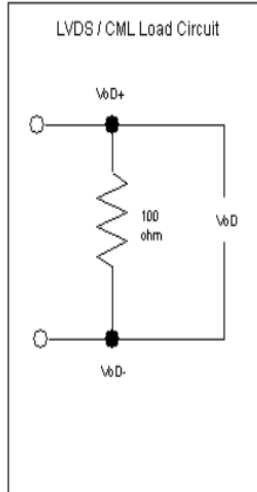
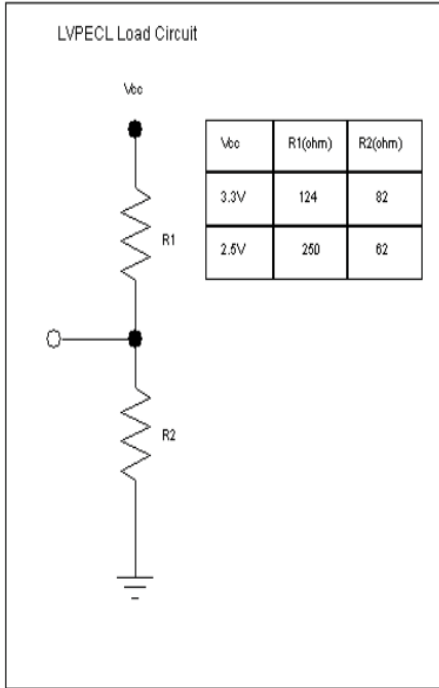
## Output Waveform



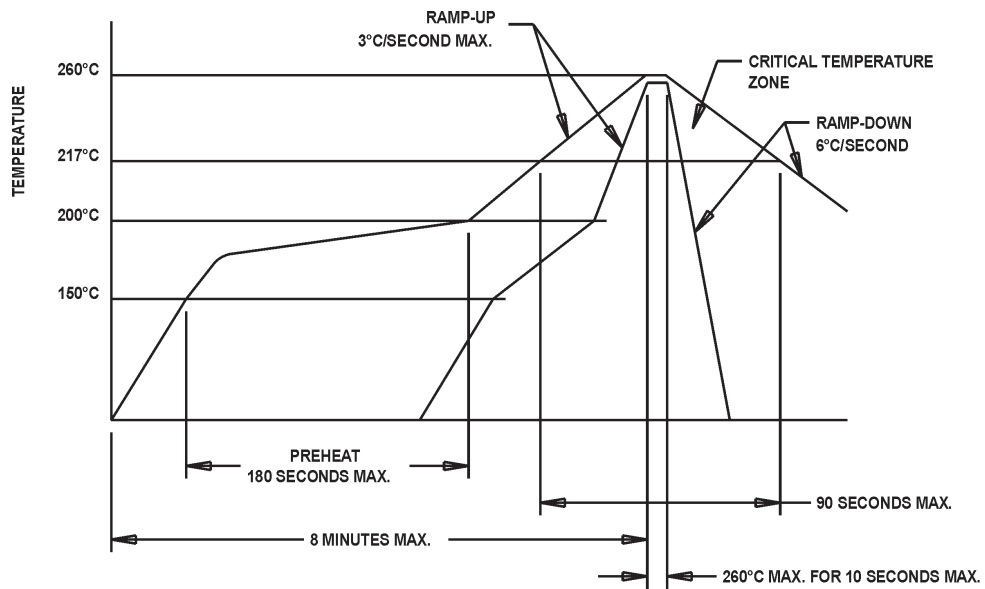
## Suggested Pad Layout



## Typical Test Circuit & Load Circuit Diagrams



## Maximum Soldering Conditions



Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions/Notes	
Frequency Range	F	10 10		1400 200	MHz MHz	LVPECL, LVDS, CML CMOS	
Operating Temperature	T <sub>A</sub>	See How to order			°C		
Storage Temperature	T <sub>STG</sub>	-55		+125	°C		
Frequency Stability		See how to order			ppm		
Frequency Tolerance at +25°C		-5.0		+5.0	ppm	at time of shiopment	
Frequency Vs. Aging		-2.0 -1.0		+ 2.0 + 1.0	ppm ppm	1 <sup>st</sup> year Thereafter(per year).	
Frequency Vs. Supply Voltage			± 0.5		ppm	5% voltage variation	
Frequency Vs. Reflow			± 0.80		ppm	2 reflows max.	
Frequency Vs. Load			± 0.5		ppm	5% supply voltage variation	
Operating Voltage	V <sub>cc</sub> /V <sub>s</sub> /V <sub>dd</sub>	3.135 2.375 1.71	3.3 2.5 1.8	3.465 2.625 1.89	V V V		
Operating Current	I <sub>cc</sub>			130 110 120 100	mA mA mA mA	LVPECL LVDS CML CMOS	
Rise/Fall Time	Tr/Tf			1.0 8	ns ns	PECL, LVPECL, LVDS CMOS	
Logic "1" Level	V <sub>OH</sub>	V <sub>CC</sub> -1.02 80% V <sub>dd</sub>			V V	LVPECL CMOS	
Logic "0" Level	V <sub>OL</sub>			V <sub>CC</sub> -1.63 20% V <sub>dd</sub>	V V	LVPECL CMOS	
Common Mode Output Voltage	V <sub>cm</sub>		1.2		V	LVDS	
Symmetry (Duty Cycle)		40 40 40		60 60 60	% % %	@ 50% V <sub>dd</sub> (CMOS) @ 50% of waveform (LVPECL) @ 1.25 V (LVDS)	
Output Voltage Level		0.7	0.95	1.2	V <sub>p-p</sub>	CML	
Tuning Range		± 5			ppm	VCTCXO only. See Note 2.	
Output Skew			20 15 20		ps ps ps	LVPECL CML LVDS	
Output Load		50 ohm to (V <sub>CC</sub> -2V) VDC 100 ohm Differential					See Note 3 LVPECL LVDS, CML
		15				pF	CMOS
Enable/Disable Function		80%		0.5 0.5	V V	Outputs enabled Outputs disabled Outputs enabled Outputs disabled	
Phase Noise (Typical)	10 Hz	100 Hz	1 kHz	10 kHz	100 kHz	Offset from carrier	
@ 622.080 MHz (LVPECL)	-60	-90	-120	-127	-133	dBc/Hz	
@ 100.000 MHz (HCMOS)	-73	-97	-123	-131	-136	dBc/Hz	
@ 50.000 MHz (HCMOS)	-80	-102	-130	-137	-141	dBc/Hz	
Jitter	Phase jitter	0.5ps (Typical)@Integrated,Bandwidth 12KHz to 20MHz ,RMS					
	Random period jitter	3.0ps (Typical)@Integrated,Bandwidth 10KHz to 1MHz ,RMS					
	Pk to Pk jitter	20.0ps (Typical)					
Shock	Per MIL-STD-202, Method 213, Condition C						
Vibration	Per MIL-STD-202, Methods 201 & 204						
Solderability	Per EIAJ-STD-002						
Hermeticity	1 X 10 <sup>-8</sup> atm cc/sec of helium (Crystal only)						
Thermal Shock	Per MIL-STD-883, Method 1011, Condition A						
Thermal Cycle	Per MIL-STD-883, Method 1010, Condition B						

Note 1: Standard ±5ppm(Max),other frequency tolerance,pls factory

Note 2: Contact factory for other Tuning Range options.

Note 3: See Load Circuit Diagram.